



Material Content Data Sheet



Sales Product Name		BTS3060TF		Issued		12. August 2019		
MA#		MA001220394						
Package		PG-TO252-3-11		Weight*		369.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.041	0.28	0.28	2817	2817
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175	
	non noble metal	iron	7439-89-6	0.215	0.06		583	
	non noble metal	copper	7440-50-8	215.017	58.20	58.28	582080	582838
	non noble metal	aluminium	7429-90-5	0.614	0.17	0.17	1662	1662
wire	non noble metal	aluminium	7429-90-5	0.614	0.17	0.17	1662	1662
encapsulation	organic material	carbon black	1333-86-4	1.282	0.35		3470	
	plastics	epoxy resin	-	22.429	6.07		60717	
	inorganic material	silicondioxide	60676-86-0	104.453	28.28	34.70	282770	346957
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10125	10125
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	246	247
solder	non noble metal	tin	7440-31-5	0.025	0.01		67	
	noble metal	silver	7440-22-4	0.031	0.01		84	
	non noble metal	lead	7439-92-1	1.189	0.32	0.34	3219	3370
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.19	5.20	51916	51984
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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